CIRCUITS MANUFACTURING 1988 ANNUAL INDEX

Automation

The Assembly Revolution, Kelvin F. Cross, Gray-Judson & Howard, May, p. 38.

Automated Wet Processing, Jerry Murray, West Coast Editor, February, p. 48.

Panels In, PCBs Out, Ed Choinski, Epicor Technology Inc., May, p. 27.

Robots at Work, Jeff Stover, Gelzer Systems Co. Inc., Greg Myers, Delco Systems Operations, and Bill Pearce, Intelledex Inc., February, p. 27.

Talk to Me, Jerry Secrest, Consultant, June, p. 65.

Part Program Files, Roger Beetlestone, Excellon Automation, December, p. 43

Bar Code

Bar Code Basics, Tammy A. Winter, York Tape and Label Co., April, p. 23.

Bar Coding Software, Ramin Khoshatefeh, Integrated Software Design Inc., August, p. 54.

Lasers Make Their Mark, Bert Williams and L. Hall Healy Jr., Videojet Systems International, April, p. 29.

A Sampling of Bar Code Products, Apr, p. 35.

Buyer's Guide

Circuits Manufacturing 1988 Buyer's Guide, October, entire

Cleaning

Keeping Boards and the Environment Clean, John Tuck, Publisher/Editor, November, p. 52.

New Cleaning Method Sends Circuit Boards Spinning, Randy Rich, Accel, November, p. 61.

Roundtable on Cleaning, John Tuck, Publisher/Editor, August, p. 48.

Dispensing

Indispensable, Jerry Murray, West Coast Editor, April, p. 41.

Drilling

A Benchmark Technique for Microdrilling, Roger Beetlestone and Russell Candell, Excellon Automation, August, p. 57.

Blind Buried Vias, Jerry Murray, West Coast Editor, April, p. 62.

Small Hole Drilling Productivity, Wojciech Kosmoski, Dynamotion, August, p. 69.

Tune-Up for Microdrilling, Ed Hendrik, Advanced Controls, August, p. 63.

Fabrication

A Benchmark Technique for Microdrilling, Roger Beetlestone and Russell Candell, Excellon Automation, August, p. 57. Blind Buried Vias, Jerry Murray, West Coast Editor, April, p.

62.
The Ceramic-Organic Bridge, Jerry Murray, West Coast Editor,

July, p. 30.

Copper and PTF Merger, Dr. Ken Gilleo, Sheldahl Inc., July, p.

The Density Problem: A Forum Discussion, Jerry Murray, West Coast Editor, November, p. 76.

How to Avoid Wet Processing, Peter Soszek, R&D, Somich Technology Inc., May, p. 21.

Panels In, PCBs Out, Ed Choinski, Epicor Technology Inc., May, p. 27.

Routes to Hi-Rel Copper, Jerry Murray, West Coast Editor, May, p. 32.

Small Hole Drilling Productivity, Wojciech Kosmoski, Dynamotion, August, p. 69.

Tune-Up for Microdrilling, Ed Hendrik, Advanced Controls, August, p. 63.

Part Program Files, Roger Beetlestone, Excellon Automation, December, p. 43

Hi-Rei

The FR-4 of the 1990s, Jerry Murray, West Coast Editor, June, p. H17.

Laser Slashes Rework and Defects, Andy Sweeney and Billy Petross, Singer Electronics Systems Div., September, p. H2.

A New Test for Leaky Connectors, James C. Sell and Michael R. Strong, Dow Corning Corp., September, p. H11.

No Failures Allowed, Terry D. Canning, Rockwell International, September, p. H8.

A Reliability Test, Werner Engelmaier, AT&T Bell Laboratories, June, p. H2.

Routes to Hi-Rel Copper, Jerry Murray, West Coast Editor, May, p. 32.

Temperature Testing to DOD-STD-2000, Jan Boyd, OK Industries Inc., June, p. H23.

Are You Ready for DOD-STD-2000?, Robert Cormack, Naval Air Engineering Center, December, p. H3

Conformal Coatings, Roger Olson, Nova Tran Corp., December, p. H8

Hi-Rel SMT Solder Joints, Werner Engelmaier, AT&T Bell Laboratories, p. H16

Hybrids

 The Ceramic-Organic Bridge, Jerry Murray, West Coast Editor, July, p. 30.
 Just a Trim, Please, Bruce Couch, Teradyne Inc., April, p. 49.

Imaging

Alignment-Limited Yields, Robert W. Allison Jr., R. A. Services, Richard W. DeMott, M. Alex Shaw and Michael W. Powell, Nikon Precision Inc., March, p. 25.

Hidden Dollars in Your Cost, Mike Juha, Excellon Photonics Div., March, p. 33.

The Paperless Trail to Zero Defects, Rudy Arp, Western Digital Corp., March, p. 38.

The Revolution that Is, Jerry Murray, West Coast Editor, January, p. 38.

Silver Tools Sent to Work, Kenneth Smith and Neil Steinberg, Du Pont Co., July, p. 22.

International

A Mexican Partnership, Jerry Murray, West Coast Editor, March, p. 44.

Materials

Coming Soon: The Ideal Laminate, Lyle R. Wallig, Du Pont Co., January, p. 25.

ANNUAL INDEX

The FR-4 of the 1990s, Jerry Murray, West Coast Editor, June, p. H17.

The Third Generation Epoxies, Art Burkhart, Hysol Electronic Chemicals, February, p. 43.

Solder Mask Selection, G. M. Tilsley and F. J. Axon, Dynachem Europe, and Larry Fisher, Dynachem USA, June, p. 75.

Three New Solder Mask Tools, Jerry Murray, West Coast Editor, November, p. 70.

Conformal Coatings, Roger Olson, Nova Tran Corp., December, p. H8

Plating

Automated Wet Processing, Jerry Murray, West Coast Editor, February, p. 48

Blind Buried Vias, Jerry Murray, West Coast Editor, April, p. 62.
Deep Hole Plating, Jerry Murray, West Coast Editor, September, p. 41.

Routes to Hi-Rel Copper, Jerry Murray, West Coast Editor, May, p. 32

Process Control

ECOs: Band-Aid Fix? Michael L. Martel, Associate Editor, September, p. 57.

Know Thy Process, Dennis Picker, Fidelis Group Inc., August, p. 42.

Laser Slashes Rework and Defects, Andy Sweeney and Billy Petross, Singer Electronics Systems Div., September, p. H2.

The Paperless Trail to Zero Defects, Rudy Arp, Western Digital Corp., March, p. 38.

Stop in the Name of Quality, Howard Gaston and James Young, AT&T, February, p. 54.

QA/Test Inspection

AOI Takes a Closer Look at Innerlayers, Jeff Rittichier, Gerber Scientific Industry Co., September, p. 46.

Checking Up on Board Quality, Fred Kear, Siemens Transmission Systems, November, p. 37.

Laser Slashes Rework and Defects, Andy Sweeney and Billy Petross, Singer Electronics Systems Div., September, p. H2.

A New Test for Leaky Connectors, James C. Sell and Michael R. Strong, Dow Corning Corp., September, p. H11.

A Reliability Test, Werner Engelmaier, AT&T Bell Laboratories, June, p. H2.

Temperature Testing to DOD-STD-2000, Jan Boyd, OK Industries Inc., June, p. H23.

Are You Ready for DOD-STD-2000?, Robert Cormack, Naval Air Engineering Center, December, p. H3

Software

Bar Coding Software, Ramin Khoshatefeh, Integrated Software Design Inc., August, p. 54 Software for Manufacturing, July, p. 26.

Soldering

Know Thy Process, Dennis Picker, Fidelis Group Inc., August, p. 42.

Sensing the Source of Wave Soldering Defects, Michael Guerra, Williamson Corp., January, p. 32.

Soldering without Cleaning, Wallace Rubin, Multicore Solders Ltd., January, p. 21.

Temperature Testing to DOD-STD-2000, Jan Boyd, OK Industries Inc., June, p. H23.

Hi-Rel SMT Solder Joints, Werner Engelmaier, AT&T Bell Laboratories, December, p. H16

SURFACE MOUNT TECHNOLOGY

Cleaning

Keeping Boards and the Environment Clean, John Tuck, Publisher/Editor, November, p. 52.

New Cleaning Method Sends Circuit Boards Spinning, Randy Rich, Accel, November, p. 61.

Fabrication

Blind Buried Vias, Jerry Murray, West Coast Editor, April, p. 62.

Pads Only, Please, Ravi K. Jain and Jeff K. Kennedy, Control Data Corp., June, p. 71.

Fine-Pitch

Fine Forming, Ronald Corey and Rudolf Nordman, Fancourt Industries Inc., and Andrew Amalfitano, Norden Systems, July, p. 41.

The Fine-Pitch Dilemma, Michael L. Martel, Associate Editor, November, p. 47.

Fine Solder Prints, Gary Freeman, MPM Corp., March, p. 58.

The Latest Developments in Fine-Pitch Pick-and-Place, Michael L. Martel, Associate Editor, November, p. 43.

JIT

CFM Solves a Worst Case, Dan Arnold, EMD Associates Inc., January, p. 61.

Materials

Fluids in a New Phase, Tom Dixon, Contributing Writer, February, p. 58.

A Paste Primer, Michael L. Martel, Conceptronic, April, p. 54. Solder Mask Selection, G. M. Tilsley and F. J. Axon, Dynachem Europe, and Larry Fisher, Dynachem USA, June, p. 75.

A Sticky Solution, Michael L. Martel, Conceptronic, February, p. 73.

Pick-and-Place

The Latest Developments in Fine-Pitch Pick-and-Place, Michael L. Martel, Associate Editor, November, p. 40.

More Machines in the Fast Lane, John Tuck, Publisher/Editor, January, p. 45.

The Flip Side of Manual Pick-and-Place, Alden D. Lewis, Conceptronic Inc., December, p. 56

Purchasing

How to Buy Without Risking Your Job, Stephen J. Dow, Austin American Technology, September, p. 62.

Vendors and Buyers as Cosuppliers, Jerry Murray, West Coast Editor, May, p. 69.

QA/Test, Inspection

Better Safe than Sorry? Alice C. Abrams, Managing Editor, Production, May, p. 43.

Bringing Test on Board, R. A. Keagy, Texas Instruments, June, p. 85.

Checking up on Board Quality, Fred Kear, Siemens Transmission Systems, November, p. 37.

Cracks: The Hidden Defect, John Maxwell, AVX Corp., November, p. 28

The Paperless Trail to Zero Defects, Rudy Arp, Western Digital Corp., March, p. 38.

ANNUAL INDEX

Quest for Test, Alice C. Abrams, Managing Editor, Production, March, p. 49.

SPC by AOI, Christopher G. Hill, Universal Instruments Corp., August, p. 35.

Reliability

No Failures Allowed, Terry D. Canning, Rockwell International, September, p. H8.

The Shape of the Future, P. Todd Alexander, Quad Systems Corp., and David C. Bello, Flextronics Southwest Inc., September, p. 68.

Repair, Rework

The Paperless Trail to Zero Defects, Rudy Arp, Western Digital Corp., March, p. 38.

Profiles in Rework, Michael L. Martel, Conceptronic, July, p. 47.

A Sticky Solution, Michael L. Martel, Conceptronic, February, p. 73.

Process Development in SMT Rework, Louis Abbagnaro, Pace Inc., December, p. 50

The Flip Side of Manual Pick-and-Place, Alden D. Lewis, Conceptronic Inc., December, p. 56

The Lowdown on Rework, Michael L. Martel, Associate Editor, December, p. 58

Soldering

Finally, Standards for SMT Reflow, Richard Charbonneau, Colorado Surface Mount Technology, November, p. 24. The Fine-Pitch Dilemma, Michael L. Martel, Associate Editor, November, p. 47.

Fine Solder Prints, Gary Freeman, MPM Corp., March, p. 58.
Finish with Solderability, Eric Fincham, Corfin Technologies, February, p. 80.

Fluids in a New Phase, Tom Dixon, Contributing Writer, February, p. 58.

Forced-Convection IR Reflow, Don DeAngelo, Heller Industries Inc., May, p. 51.

IR Reflow Soldering Equipment, May, p. 54.

Lamp IR Soldering, Norman R. Cox, Research Inc., May, p. 43.

Panel/Convection IR Reflow, Phil Zarrow, Vitronics Corp., May, p. 47.

A Paste Primer, Michael L. Martel, Conceptronic, April, p.

Tailor Made Soldering, Billy R. Cobb, Texas Instruments, July, p. 52.

Standards

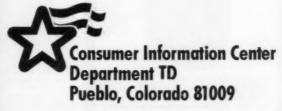
Finally, Standards for SMT Reflow, Richard Charbonneau, Colorado Surface Mount Technology, November, p. 24.
The More the Merrier, Tom Dixon, Contributing Writer, August, p. 54.

Turnkey Assembly

Turn the Key and Go? John Tuck, Publisher/Editor, February, p. 67.



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